

## Advanced Spectral Defect Detection and Metrology

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### Applications:

- Wafer level defect detection & measurement
- Process development or production
- Precision MEMS and HD component inspection
- Advanced microelectronics package inspection

### Features:

- manual / automatic operation
- up to 100 defects/measurements per second
- 200mm/second part staging speed
- up to 300mm wafers
- vision based parts alignment
- high accuracy stage 0.02 um linear encoder resolution
- high resolution CCD array with software controlled backlighting
- Win 7 with RMS vision systems metrology software
- custom operator interface, data formats, reports
- power requirements: 230Vac, 15A

### Benefits:

- fast measurements
- dual production / engineering use
- extensive defect detection and classification
- integrated precision dimensional metrology
- color graphics and CAD drawing import / export
- customized software, optics and handling options